文件编号HXA-L04-24(05)发行日期2015年8月27日

承认规格书

种类:功率电感

系列号: <u>HXCD54N-Series</u>

客户料号:_____

客	户	承	认	栏

承认日期

年 月

日

(贵司承认后请签署一份返回华信安电子,谢谢!)

厦门华信安电子科技有限公司技术质量部

承 认	确 认	作 成
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SMD Power Inductor

HXCD54N-Series

	ECN HISTORY LIST							
REV	DATE	DESCRIPTION	APPROVED	CHECKED	DRAWN			
1.0	15/8/27	新发行	龙梅	梁峰	王亮			
备								
注								
/工								



SMD Power Inductor

HXCD54N-Series

1. Features

- 1. Small and Low profile inductor
- 2. It corresponds to High current.
- 3. Simple and Shield structure.
- 4. Available tape and reel for auto insertion.
- 5. 100% Lead(Pb)-Free and RoHS compliant.



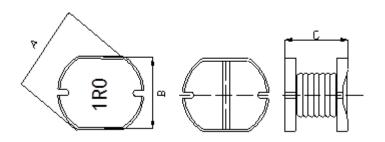


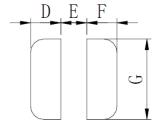
2. Applications

-For small DC/DC converter(cellular phone,LCD/LED/OLED display, HDD, DSC etc)

3. Dimensions

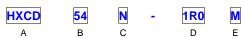
Recommendend Land pattern





	A(mm)	B(mm)	C(mm)	D(mm)	E(mm)	F(mm)	G(mm)
HXCD54N	5.8±0.3	5.2±0.3	4.5±0.3	2.15	1,7	2.15	5.5

4. Part Numbering



A: Series

B: Dimension

A*B*C

C: Type D: Inductance

1R0=1.0uh 100=10uh,101=100uh,102=1000uh E: Inductance Tolerance

 $K=\pm 10\%$, $M=\pm 20\%$,

marking direction cannot decide polarity. Color: Black, unidirectional.

No magnetic shielding



5. Specification

	Inductance			Rated	current	DCR
Part Number	L0 (uH) @ 0 A	Tolerance	Frequency (Hz/0.25V)	Saturation current I sat (A)	Tempetature current I rms (A)	(mΩ) @25℃ ±20%.
HXCD54N-1R0M	1.0	±20%	100K	5.90	4.88	25.0
HXCD54N-1R5M	1.5	±20%	100K	5.30	4.55	28.0
HXCD54N-2R2M	2.2	±20%	100K	4.90	3.43	35.0
HXCD54N-3R3M	3.3	±20%	100K	4.30	3.00	40
HXCD54N-4R7M	4.7	±20%	100K	4.00	2.90	40
HXCD54N-6R8M	6.8	±20%	100K	3.30	2.65	70
HXCD54N-100M	10.0	±20%	100K	2.40	1.95	110
HXCD54N-150M	15.0	±20%	100K	2.15	1.70	150
HXCD54N-220M	22.0	±20%	100K	1.80	1.45	180
HXCD54N-330M	33.0	±20%	100K	1.70	1.30	250
HXCD54N-470M	47.0	±20%	100K	1.35	1.00	380
HXCD54N-680M	68.0	±20%	100K	0.80	0.60	480
HXCD54N-101K	100.0	±10%	100K	0.65	0.50	730
HXCD54N-121K	120.0	±10%	100K	0.48	0.45	930
HXCD54N-151K	150.0	±10%	100K	0.55	0.40	1200
HXCD54N-221K	220.0	±10%	100K	0.50	0.35	1650
HXCD54N-331K	330.0	±10%	100K	0.40	0.28	3200
HXCD54N-471K	470.0	±10%	100K	0.32	0.20	3100
HXCD54N-681K	680.0	±10%	100K	0.26	0.18	5100
HXCD54N-821K	820.0	±10%	100K	0.22	0.13	5300
HXCD54N-102K	1000.0	±10%	100K	0.20	0.11	5900

Note:

- 1. All test data referenced to 25℃ ambient.
- $2. \ \ \text{Testing Instrument}: \text{L/Q: HP4284A,CH11025,CH3302,CH1320 ,CH1320S LCR METER/Rdc:CH16502,Agilent33420A MICRO OHMMETER.}$
- 3. Heat Rated Current (Irms) will cause the coil temperature rise approximately $\,\Delta\,t$ of 40°C (keep 1min.).
- 4. Saturation Current (Isat) will cause L0 $\,$ to drop $\,$ 30% typical. (keep quickly).
- 5. The part temperature (ambient + temp rise) should not exceed 125°C under worst case operating conditions. Circuit design, component, PCB trace size and thickness, airflow and other cooling provisions all affect the part temperature. Part temperature should be verified in the end application.
- 6 Spacial inquirios hacidos tha ahova common usad tunos can ha mat on vour requirement





NO	Items	Materials	
1	Core	Ferrite core.	
2	Wire	Polyester Wire or equivalent.	
3	Ink	Halogen-free ketone	

7. Reliability and Test Condition

Item	Performance	Test Condition
Operating temperature	-40~+125°C	
Storage temperature and Humidity range	-10~+40°C,50~60%RH (Product without taping)	
Electrical Performance Tes	st	
Inductance	Refer to standard electrical characteristics list.	HP4284A,CH11025,CH3302,CH1320,CH1320S LCR Meter.
DCR	Telefi to standard electrical characteristics list.	CH16502,Agilent33420A Micro-Ohm Meter.
Saturation Current (Isat)	△L30% typical.	Saturation DC Current (Isat) will cause L0 to drop \triangle L(%)(keep quickly).
Heat Rated Current (Irms)	Approximately △T≦40°C	Heat Rated Current (Irms) will cause the coil temperature rise $\Delta T({}^{\circ}\!\!C)$ without core loss. 1.Applied the allowed DC current(keep 1 min.). 2.Temperature measured by digital surface thermometer
Reliability Test		
High Temperature Exposure Test		Temperature:125±2°C. Duration:1000±12hrs. Measured at room temperature after placing for 2 to 3hrs. (MIL-PRF-27)
Low Temperature Life Test		Temperature:-40±2°C. Duration:500±12hrs. Measured at room temperature after placing for 2 to 3hrs.
Biased Humidity Test		Humidity:85±3%RH. Temperature:85±2°C. Duration:1000±12hrs. Measured at room temperature after placing for 2 to 3hrs (AEC-Q200-REV C)
Thermal shock test	Electric specifications should be satisfied	Condition for 1 cycle Step1:-40+0 / -2°C 15 \pm 1 min. Step2:Room temperature within \leq 0.2 min. Step3:+125 \pm 2 / -0°C 15 \pm 1 min. Number of cycles:300 Measured at room temperature after placing for 2 to 3 hrs. (AEC-Q200-REV C)
Vibration test		Frequency: 10-2000-10Hz for 20 min. Amplitude: Parts mounted within 2" from any secure point. Directions and times: X, Y, Z directions for 20 min. This cycle shall be performed 12 times in each of three mutually perpendicular directions (Total 12hours). (MIL-STD-202 Method 204 D Test condition B)
Reflow test		Pre-heat: $150\pm5^{\circ}$ C Duration: 5 minutes Temperature: $260\pm5^{\circ}$ C, 5~10 seconds (IPC/JEDEC J-STD-020C)
Solder test	Terminals should be covered by over 95% solder on visual inspection	After dip into flux, dip into solder 235±5℃, 4±1seconds Flux \ solder for lead free (ANSI /J-STD-002C Method B)



8. Soldering and Mounting

(1) Soldering

Mildly activated rosin fluxes are preferred. The minimum amount of solder can lead to damage from the stresses caused by the difference in coefficients of expansion between solder, chip and substrate. ISND terminations are suitable for re-flow soldering systems. If hand soldering cannot be avoided, the preferred technique is the utilization of hot air soldering tools.

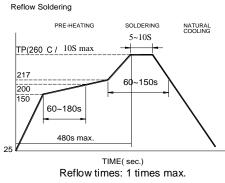
(2) Solder re-flow:

Recommended temperature profiles for re-flow soldering in Figure 1.

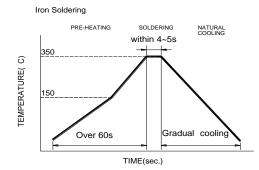
(3) Soldering Iron:

Products attachment with a soldering iron is discouraged due to the inherent process control limitations. In the event that a soldering iron must be employed the following precautions are recommended.

- Preheat circuit and products to 150℃
 Never contact the ceramic with the iron tip
 Use a 20 watt soldering iron with tip diameter of 1.0mm
- · 355°C tip temperature (max) · 1.0mm tip diameter (max) · Limit soldering time to 4~5sec.



imes: 1 times max. Fig.1



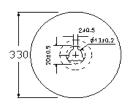
Iron Soldering times: 1 times max.

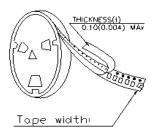
Fig.2



9. Packaging Information

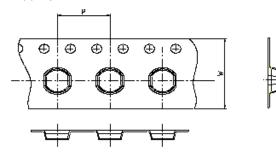
(1) Reel Dimension

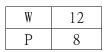




Туре	A(mm)	B(mm)	C(mm)	D(mm)
13"x12mm	12.5±0.5	100±2	13.5±0.5	330±3.0

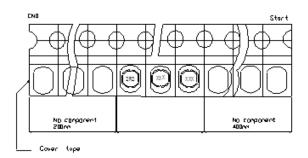
(2) Tape Dimension

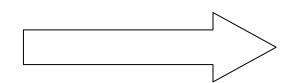




Unreeling

Directio

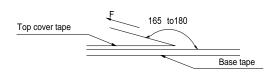




(3) Packaging Quantity

HXCD	54
Chip / Reel	1500

(4) Tearing Off Force



The force for tearing off cover tape is 10 to 130 grams in the arrow direction under the following conditions(referenced ANSI/EIA-481-C-2003 of 4.11 stadnard).

Room Temp.	Room Humidity	Room atm	Tearing Speed
(℃)	(%)	(hPa)	mm/min
5~35	45~85	860~1060	300

Application Notice

- · Storage Conditions
 - To maintain the solderability of terminal electrodes:
 - 1. ISND products meet IPC/JEDEC J-STD-020D standard-MSL, level 1.
 - 2. Temperature and humidity conditions: Less than 40 $^{\circ}\mathrm{C}$ and 60% RH.
 - $\overline{\mbox{3.}}$ Recommended products should be used within 12 months form the time of delivery.
 - 4. The packaging material should be kept where no chlorine or sulfur exists in the air.
- · Transportation
 - 1. Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
 - 2. The use of tweezers or vacuum pick up is strongly recommended for individual components.
 - 3. Bulk handling should ensure that abrasion and mechanical shock are minimized.



单击下面可查看定价,库存,交付和生命周期等信息

>>ISND(华信安)